

Material Composition Specification

TO-78 Case



Device average mass 1.0 g
 Fluctuation margin +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	0.1%	1.0	doped Si	7440-21-3	0.1%	1.0	998
bond wire	aluminum	0.0001%	0.001	Al	7429-90-5	0.0001%	0.001	1
header	steel	59.9%	600.2	Fe	7439-89-6	35.03%	351	350,303
				glass	Proprietary	24.75%	248	247,507
				Au	7440-57-5	0.06%	0.6	599
				Ni	7440-02-0	0.06%	0.6	599
can	metal alloy	39.86%	399.39	Fe	7439-89-6	39.82%	399	398,207
				Ni	7440-02-0	0.039%	0.39	389
can plating*	matte tin**	0.08%	0.8	Sn	7440-31-5	0.08%	0.8	798
termination plating*	matte tin**	0.06%	0.6	Sn	7440-31-5	0.06%	0.6	599

*For Lead Free termination plating, add suffix "PB FREE" to part number.

**Contact the Central Semiconductor Sales Department for tin/lead plating availability.

Disclaimer

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R4 (16-July 2018)